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To the Director of the U.S. Patent and Trademark

the attached documents or the address(es) below..

U.S. PTO
22386 10918407

1. Name of conveying party(ies)/Execution Date(s):

Myung Jin YIM
Jin Sang HWANG

Execution Date(s): July 16, 2004

Additional name(s) of conveying party(ies) attached?

attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

NAME: TELEPHUS INC.

ADDRESS: 25-11 Jang-dong, Yuseong-gu
Daejeon-city, Republic of Korea

3. Name of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

Additional name(s) & addresses(es) attached?

☐ Yes ☒ No

4. Application number(s) or patent number(s):

A. Patent Application No.(s)

This document is being filed together with a new application

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: G. Franklin Rothwell
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 Attorney Docket No.: 1751-363

6. Total number of applications and patents involved: One7. Total fee (37 CFR 3.41): . . . \$ 40.00

- ☒ Enclosed
☐ Authorized to be charged to deposit account
☐ None required (government interest not affecting title)

8. Deposit account number: 02-2135Authorized User Name G. Franklin Rothwell

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9. Signature.

G. F. Rothwell

Signature

8.16.04

Date

G. Franklin Rothwell
Name of Person SigningTotal number of pages including cover sheet, attachments and documents: 2

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PATENT
REEL: 015706 FRAME: 0896

ASSIGNMENT OF PATENT APPLICATIONWHEREAS, I/we, YIM, Myung Jin, a citizen of Republic of Korea,*First Named Inventor*residing at 1-1107 Jayeon Apt. 393-3 Gung-dong, Yuseong-gu, Daejeon-city, Rep. of Korea,*Address*HWANG, Jin Sang, a citizen of Republic of Korea*Second named Inventor, If any*residing at 6-805 Hangaram Apt., 834 Tanbang-dong, Seo-gu, Daejeon-city, Rep. of Korea*Address*

ASSIGNOR(S), am/are the inventor(s) of an invention in (insert title)

MULTILAYERED ANISOTROPIC CONDUCTIVE ADHESIVE FOR FINE PITCH

for which I/we have executed an application for Letters Patent of the United States,

(Check One) ☒ of even date herewith;
☐ U.S. Serial Number _____ filed _____;
☐ International Application No. _____ filed _____;

and

WHEREAS, TELEPHUS INC., a Korean Corporation of 25-11 Jang-dong, Yuseong-gu, Daejeon-city, Rep. of Korea*Assignee**Citizenship or Corporate Status**Address*

ASSIGNEES, are desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, In consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said ASSIGNOR(S) have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE HEREBY covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the ASSIGNEES.

IN TESTIMONY WHEREOF, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

YIM, Myung Jin YIM, Myung Jin L.S. Date July 16, 2004, 2004HWANG, Jin Sang Hwang, Jin Sang L.S. Date July 16, 2004, 2004

Witness:

Kim, Hyun Jung KIM, Hyun Jung*Name*12 August 2004*Date*Kim Joo Hyun KIM, Joo Hyun*Name*12. Aug. 2004*Date*